

**AMENDMENTS TO THE SPECIFICATION**

**Please replace the paragraph bridging pages 124 and 125 with the following  
amended paragraph:**

As the metal particles, there can be used copper, gold, silver, aluminum, nickel, titanium, chromium, tin/lead, palladium, platinum and the like. The particle diameter of those metal particles is preferably 0.1 to 50  $\mu\text{m}$ . This is because [[,]] the surface of copper is oxidized to worsen wettability against the resin when the diameter is less than 0.1  $\mu\text{m}$ , while the printing efficiency becomes worse when the diameter is over 50  $\mu\text{m}$ . The addition amount of the metal particles is preferably 30 to 90 wt.%. This is because the adhesion of cover plating becomes worse when the amount is less than 30 wt.%, while the printing efficiency becomes worse when the amount is over 90 wt.%.